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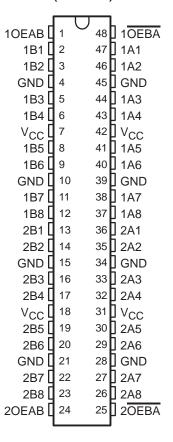
- Members of the Texas Instruments Widebus™ Family
- Inputs are TTL-Voltage Compatible
- Flow-Through Architecture Optimizes
 PCB Layout
- Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise
- EPIC[™] (Enhanced-Performance Implanted CMOS) 1-µm Process
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) Packages Using 25-mil Center-to-Center Pin Spacings and 380-mil Fine-Pitch Ceramic Flat (WD) Packages Using 25-mil Center-to-Center Pin Spacings

description

The 'ACT16623 are 16-bit transceivers designed for asynchronous two-way communication between data buses. The control-function implementation allows for maximum flexibility in timing.

These devices can be used as two 8-bit transceivers or one 16-bit transceiver. They allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the output-enable (OEBA and OEAB) inputs. The output-enable inputs can be used to disable the device so that the buses are effectively isolated.

54ACT16623 . . . WD PACKAGE 75ACT16623 . . . DL PACKAGE (TOP VIEW)



The dual-enable configuration gives the bus transceiver the capability to store data by simultaneously enabling OEBA and OEAB. Each output reinforces its input in this transceiver configuration. When both control inputs are enabled and all other data sources to the two sets of bus lines are at high impedance, the bus lines remain at their last states.

The 74ACT16623 is packaged in TI's shrink small-outline package, which provides twice the functionality of standard small-outline packages in the same printed-circuit-board area.

The 54ACT16623 is characterized for operation over the full military temperature range of –55°C to 125°C. The 74ACT16623 is characterized for operation from –40°C to 85°C.



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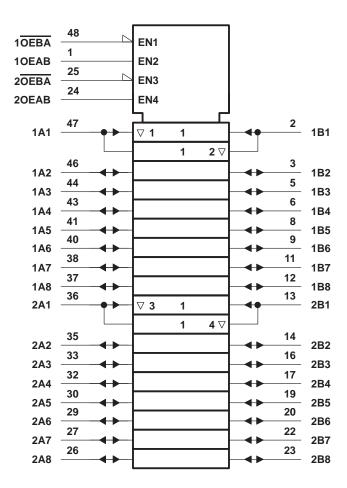


SCAS152A – JANUARY 1991 – REVISED APRIL 1996

FUNCTION TABLE (each 8-bit section)

INP	UTS	OPERATION
OEBA	OEAB	OPERATION
L	L	B data to A bus
Н	Н	A data to B bus
Н	L	Isolation
L	Н	B data to A bus, A data to B bus

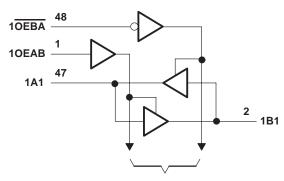
logic symbol†

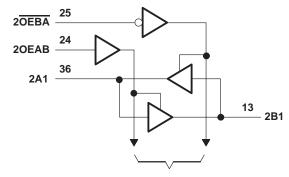


[†]This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



logic diagram (positive logic)





To Seven Other Channels

To Seven Other Channels

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	0.5 V to 7 V
Input voltage range, V _I (see Note 1)0	$.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Output voltage range, V _O (see Note 1)0	$.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Input clamp current, $I_{ K }(V_{ } < 0 \text{ or } V_{ } > V_{CC})$	±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC})	±50 mA
Continuous output current, $I_O(V_O = 0 \text{ to } V_{CC})$	±50 mA
Continuous current through V _{CC} or GND	±400 mA
Maximum power package dissipation at $T_A = 55^{\circ}C$ (in still air) (see Note 2): DL package	1.2 W
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

recommended operating conditions (see Note 3)

		54ACT16623			74	23	UNIT	
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage (see Note 4)	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2		CV	2			V
VIL	Low-level input voltage		FL	0.8			0.8	V
٧ _I	Input voltage	0	Q	VCC	0		VCC	V
VO	Output voltage	0	Ć	VCC	0		VCC	V
loh	High-level output current	40	Š	-24			-24	mA
loL	Low-level output current	40		24			24	mA
Δt/Δν	Input transition rise or fall rate	0		10	0		10	ns/V
TA	Operating free-air temperature	-55		125	-40		85	°C

NOTES: 3. Unused inputs should be connected to V_{CC} through a pullup resistor of approximately 5 k Ω or greater.

4. All V_{CC} and GND pins must be connected to the proper power supply.



SCAS152A – JANUARY 1991 – REVISED APRIL 1996

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DAI	RAMETER	TEST CONDITIONS	V	T,	Δ = 25°C		54ACT	16623	74ACT	16623	UNIT
PAI	RAMETER	TEST CONDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNII
		Jour - 50 uA	4.5 V	4.4			4.4		4.4		
		I _{OH} = -50 μA	5.5 V	5.4			5.4		5.4		
Vон		1011 - 24 mA	4.5 V	3.94			3.8		3.8		V
		I _{OH} = -24 mA	5.5 V	4.94			4.8		4.8		
		I _{OH} = -75 mA [†]	5.5 V				3.85	4	3.85		
		I FO.11A				0.1		0/1		0.1	
		I _{OL} = 50 μA	5.5 V			0.1		0.1		0.1	
VOL		la 24 mA	4.5 V			0.36	1	0.44		0.44	V
		I _{OL} = 24 mA	5.5 V			0.36	5	0.44		0.44	
		I _{OL} = 75 mA [†]	5.5 V				Q ₀	1.65		1.65	
II	Control inputs	V _I = V _{CC} or GND	5.5 V			±0.1	Ya	±1		±1	μΑ
loz	A or B ports	V _O = V _{CC} or GND	5.5 V			±0.5		±5		±5	μΑ
Icc		$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			8		80		80	μΑ
Δl _{CC} ‡		One input at 3.4 V, Other inputs at V _{CC} or GND	5.5 V			0.9		1		1	mA
Ci	Control inputs	V _I = V _{CC} or GND	5 V		4.5						pF
C _{io}	A or B ports	$V_O = V_{CC}$ or GND	5 V		16						pF

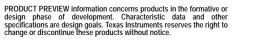
T Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	T,	λ = 25°C	;	54ACT	16623	74ACT	16623	UNIT
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	A or B B or A		4.2	7.3	9.5	4.2	10.4	4.2	10.4	ns
t _{PHL}	AOIB	BUIA	3.1	7.3	9.5	3.1	10.3	3.1	10.3	115
^t PZH	OEBA	А	2.7	6.8	8.8	2.7	9.5	2.7	9.5	ns
tpZL	OEBA	A	3.5	8.2	10.2	3.5	11.1	3.5	11.1	115
^t PHZ	OEDA	OEBA A	6	9.6	11.3	6	12	6	12	ns
t _{PLZ}	OEBA		5.3	8.6	10.3	5.3	10.7	5.3	10.7	115
^t PZH	OEAB	В	4.1	6.9	8.7	4.1	9.3	4.1	9.3	ns
^t PZL	OLAB	Ь	5.1	7.9	9.7	5.1	10.6	5.1	10.6	115
^t PHZ	OEAB	OEAB B		8.2	10.2	5.1	10.4	5.1	10.4	ns
t _{PLZ}	OLAB	, o	4.4	7.4	9.3	4.4	9.5	4.4	9.5	113

operating characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd} Power dissipation capacitance per transceiver	Outputs enabled	Cı = 50 pF. f = 1 MHz	56	nE
	Power dissipation capacitance per transceiver	Outputs disabled	$C_L = 50 \text{ pF}, \qquad f = 1 \text{ MHz}$	11

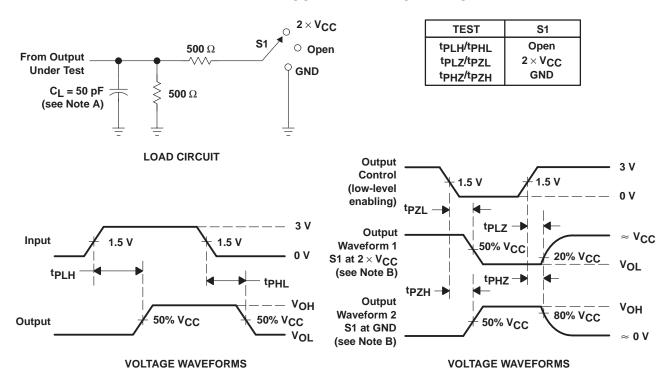




[‡] For I/O ports, the parameter IOZ includes the input leakage current.

SCAS152A - JANUARY 1991 - REVISED APRIL 1996

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \ \Omega$, $t_f = 3 \ ns$, $t_f = 3 \ ns$.
- D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
74ACT16623DL	LIFEBUY	SSOP	DL	48	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT16623	
74ACT16623DLR	ACTIVE	SSOP	DL	48	1000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT16623	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





_		
		Dimension designed to accommodate the component width
	B0	Dimension designed to accommodate the component length
	K0	Dimension designed to accommodate the component thickness
	W	Overall width of the carrier tape
ı	P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74ACT16623DLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1

www.ti.com 5-Jan-2022



*All dimensions are nominal

Device	Package Type	Package Drawing Pins		SPQ	Length (mm)	Width (mm)	Height (mm)	
74ACT16623DLR	SSOP	DL	48	1000	367.0	367.0	55.0	

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
74ACT16623DL	DL	SSOP	48	25	473.7	14.24	5110	7.87

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